

LOCTITE[®] 370™

July 2005

PRODUCT DESCRIPTION

LOCTITE[®] 370[™] provides the following product characteristics:

Technology	Acrylic					
Chemical Type	Polyurethane acrylate					
Appearance (uncured)	Transparent light yellow to dark amber colored liquid ^{LMS}					
Components	One component - requires no mixing					
Viscosity	Medium					
Cure	Ultraviolet (UV) light					
Cure Benefit	Production - high speed curing					
Application	Encapsulating or Tacking					

 $\text{LOCTITE}^{\textcircled{8}}$ 370 $^{\texttt{TM}}$ is designed for tacking or encapsulating wires or terminals, protecting them from atomospheric conditions.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Specific Gravity @ 25 °C1.1Flash Point - See MSDSViscosity, Brookfield - RVT, 25 °C, mPa·s (cP):
Spindle 3, speed 10 rpm5,500 to 8,500LMS

TYPICAL CURING PERFORMANCE

LOCTITE[®] 370TM is cured when exposed to UV radiation at 365nm. To obtain a full cure on surfaces exposed to air, radiation at 250nm is also required. The speed of cure will depend on the UV intensity as measured at the product surface. Typical cure condition is 5-10 seconds at 100mW/cm² using a medium pressure, quartz envelope, mercury vapor lamp.

Tack Free Time

Tack Free Time is the time required to achieve a tack free surface.

Tack Free Time, seconds:	
20 mW/cm ² @ 365 nm	≤10 ^{LMS}
100 mW/cm ² @ 365 nm	2

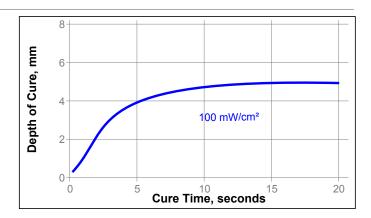
Fixture Time

Fixture time is defined as the time to develop a shear strength of 0.1 $\ensuremath{\text{N/mm}^2}$.

UV Fixture Time, ISO 4587, Glass microscope slides,	seconds:
10 mW/cm² @ 365 nm	3
100 mW/cm² @ 365 nm	1

Depth of Cure

The graph below shows the increase in depth of cure with time at 100mW/cm^2 as measured from the thickness of the cured pellet formed in a 15mm diameter PTFE die.



TYPICAL PROPERTIES OF CURED MATERIAL Physical Properties

Coefficient of Thermal Expansion, ASTM D 696, K ⁻¹	100×10⁻⁰
Coefficient of Thermal Conductivity ASTM C 177,	0.1
W/(m·K)	
Shore Hardness, ISO 868, Durometer D	45 to 80 ^{LMS}
Electrical Dranautica	
Electrical Properties	
Dielectric Breakdown Strength, IEC 60243-1, kV/mm	20
Volume Resistivity, IEC 60093, Ω·cm	5×10 ¹²
Dielectric Constant / Dissipation Factor, IEC 60250:	

TYPICAL PERFORMANCE OF CURED MATERIAL Adhesive Properties

Cured @ 100 mW/cm² @ 365 nm for 20 seconds Tensile Strength, ISO 6922: Steel pin to Glass N/mm² 3 to 7

(psi) (435 to 1,015)

5/0.04

TYPICAL ENVIRONMENTAL RESISTANCE

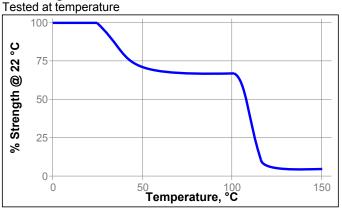
Cured @ 100 mW/cm² @ 365 nm for 20 seconds plus 1 week @ 22 $^\circ\text{C}$

Tensile Strength, ISO 6922: Steel pin (grit blasted) to Glass

Steel pill (gilt blasted) to Gla

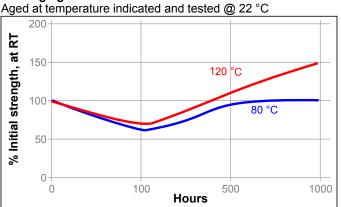
Hot Strength

1 kHz





Heat Aging



Chemical/Solvent Resistance

Aged under conditions indicated and tested @ 22 °C.

		% of initial strength		
Environment	°C	100 h	500 h	1000 h
Gasoline	22	70	40	40
1,1,1 Trichloroethane	22	100	100	100
Freon TA	22	80	90	90
Industrial methylated spirits	22	40	0	0
Heat/humidity 90% RH	40	0	0	0

GENERAL INFORMATION

This product is not recommended for use in pure oxygen and/or oxygen rich systems and should not be selected as a sealant for chlorine or other strong oxidizing materials.

For safe handling information on this product, consult the Material Safety Data Sheet (MSDS).

Directions for use

- 1. This product is light sensitive; exposure to daylight, UV light and artificial lighting should be kept to a minimum during storage and handling.
- 2. The product should be dispensed from applicators with black feedlines.
- 3. For best performance bond surfaces should be clean and free from grease.
- 4. Cure rate is dependent on lamp intensity, distance from light source, depth of cure needed or bondline gap and light transmittance of the substrate through which the radiation must pass.
- 5. Recommended intensity for cure in bondline situation is 5 mW/cm² minimum (measured at the bondline) with an exposure time of 4-5 times the fixture time at the same intensity.
- For dry curing of exposed surfaces, higher intensity UV is required (100 mW/cm²).
- 7. Cooling should be provided for temperature sensitive substrates such as thermoplastics.
- 8. Plastic grades should be checked for risk of stress cracking when exposed to liquid adhesive.
- 9. Excess uncured adhesive can be wiped away with organic solvent (e.g. Acetone).
- 10. Bonds should be allowed to cool before subjecting to any service loads.

Loctite Material Specification^{LMS}

LMS dated September 1, 1995. Test reports for each batch are available for the indicated properties. LMS test reports include selected QC test parameters considered appropriate to specifications for customer use. Additionally, comprehensive controls are in place to assure product quality and consistency. Special customer specification requirements may be coordinated through Henkel Quality.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: 8 °C to 21 °C. **Storage below** 8 °C or **greater than 28** °C **can adversely affect product properties**. Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

(°C x 1.8) + 32 = °F kV/mm x 25.4 = V/mil mm / 25.4 = inches μ m / 25.4 = mil N x 0.225 = lb N/mm x 5.71 = lb/in N/mm² x 145 = psi MPa x 145 = psi N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP

Note

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits. The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

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Reference 1.1

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Solder category:

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Other Similar products are found below :

 600YSY
 701-2758
 707-1746
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 707-1813
 707-1831
 707-1850
 707-1852
 13-217-3-01
 P10695
 SN63WRAP3

 .022-1-LB
 24-6040-0007
 DAC-061
 701-2089
 707-0285
 707-0366
 707-0441-26
 707-1774
 707-1810
 24-6337-9727
 601Y
 24-9574-7619

 24-4060-2437
 14-6040-0125
 04-0595-0000
 5901003
 631960
 SW02-10
 S2626-O-T
 8055
 5760140
 TRWR-204
 1152
 EC2002M-1
 WPT17

 WS6016
 760-2028
 8001115
 8001073
 8001495
 41-096-0203N
 ART.AGT-030
 389289
 54068
 ECO 1 (SNCU1) FLUX B2.1 0,8 MM 250G

 ECO3 (SNCU3) FLUX B2.1 0,8 MM 250 G.
 ECO3 (SNCU3) FLUX B2.1 0,8 MM 1000 G.
 ECO4 (SNAG3CU0.5) FLUX B2.1 0,8 MM 1000G